MBR820F - MBR8100F

8.0A SCHOTTKY BARRIER RECTIFIER

Features

- Power Schottky Barrier Chip
- Guard Ring for Transient Protection
- Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- High Surge Current Capability
- Epoxy Meets UL 94V-0 Classification
- Ideally Suited for Use in High Frequency SMPS, Inverters and As Free Wheeling Diodes

Mechanical Data

Case: ITO-220A, Full Molded PlasticTerminals: Plated Leads Solderable per

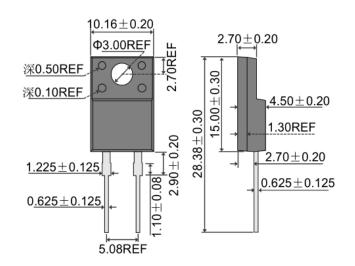
MIL-STD-202, Method 208 Polarity: See Diagram

Weight: 1.9 grams (approx.)Mounting Position: Any

Mounting Torque: 0.6 N.m Max.

Lead Free: For RoHS / Lead Free Version

ITO-220AC





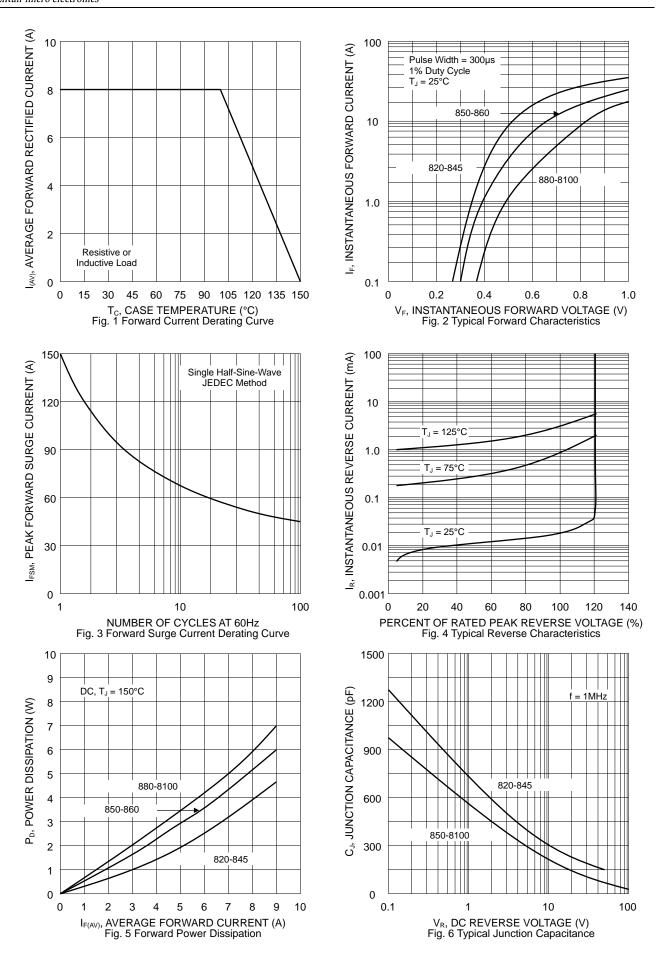
Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	MBR 820F	MBR 830F	MBR 840F	MBR 845F	MBR 850F	MBR 860F	MBR 880F	MBR 8100F	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	VRRM VRWM VR	20	30	40	45	50	60	80	100	V
RMS Reverse Voltage	VR(RMS)	14	21	28	32	35	42	56	70	V
Average Rectified Output Current @T _C = 100°C	lo	8.0							Α	
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	IFSM	150							А	
Forward Voltage @I _F = 8.0A	VFM	0.55			0.75		0.	85	V	
Peak Reverse Current $@T_J = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_J = 100^{\circ}C$	IRM	0.2 20 mA							mA	
Typical Junction Capacitance (Note 1)	Cı	450			350				pF	
Thermal Resistance Junction to Ambient Thermal Resistance Junction to Case	R JA R JC	75 5.0							°C/W	
RMS Isolation Voltage, t = 1 min	Viso	1500						V		
Operating and Storage Temperature Range	ТJ, Tsтg	-55 to +150							°C	

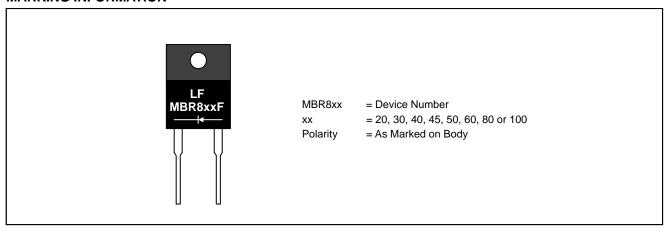
Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

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MARKING INFORMATION



PACKAGING INFORMATION

BULK

Tube Size	Quantity	Inner Box Size	Quantity	Carton Size	Quantity	Approx. Gross Weight (KG)
L x W x H (mm)	(PCS)	L x W x H (mm)	(PCS)	L x W x H (mm)	(PCS)	
525 x 31 x 6	50	558 x 150 x 40	1,000	570 x 235 x 170	5,000	11.85

RECOMMENDED SCREW MOUNTING ARRANGEMENT

The full molded plastic package affords a major reduction of hardware as compared to a standard TO-220 package. However, precautions should be made in mounting procedure.

A conical washer should be used to apply proper force to the device. Screw should not be tightened with any type of air-forced torque or equipment that may cause crack on device package.

A layer of thermal grease or thermal pad in the interface will be considerably helpful for heat dissipation.

